

RESPONSE TO RESTRICTION REQUIREMENT

Serial Number: 10/623,788

Filing Date: July 21, 2003

Title: STRAINED SEMICONDUCTOR BY FULL WAFER BONDING

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Dkt: 1303.109US1

REMARKS

In the Restriction Requirement mailed September 30, 2005, the Examiner has restricted the claims to one of the following inventions under 35 U.S.C. 121:

- I. Claims 1-53, drawn to a method of forming a wafer; and
- II. Claims 54-65, drawn to a wafer structure.

Applicant elects, without traverse, Group I, claims 1-53.

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CONCLUSION

Applicant respectfully submits that the claims are in condition for allowance, and notification to that effect is earnestly requested. The Examiner is invited to telephone Applicant's attorney at (612) 373-6960 to facilitate prosecution of this application.

If necessary, please charge any additional fees or credit overpayment to Deposit Account No. 19-0743.

Respectfully submitted,

LEONARD FORBES ET AL.

By their Representatives,

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.
P.O. Box 2938
Minneapolis, MN 55402
(612) 373-6960

Date 10-31-05 By 
Marvin L. Beekman
Reg. No. 38,377

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Mail Stop Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on this 31 day of October, 2005.

Name KACIA LEE


Signature